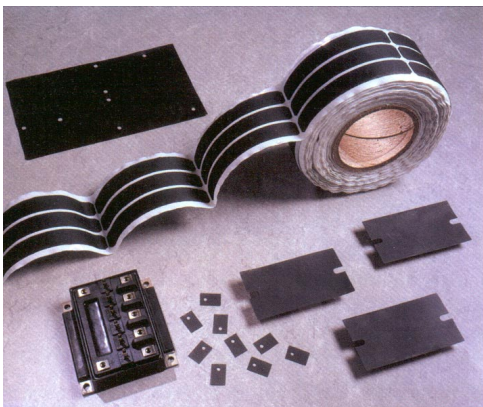


Easy to Handle, Greaseless Thermal Interface

Features and Benefits

- Thermal impedance
0.35°C-in²/W (@50 psi)
- Withstands processing stresses
- Conforms to surface textures
- May be installed prior to soldering and cleaning without worry



Bergquist Q-Pad 3 eliminates problems associated with thermal grease such as contamination of electronic assemblies and reflow solder baths. Q-Pad 3 may be installed prior to soldering and cleaning, without worry. When clamped between two surfaces, the elastomer conforms to surface textures thereby creating an air free interface between heat generating components and heat sinks.

Fiberglass reinforcement enables Q-Pad 3 to withstand processing stresses without losing physical integrity.

Typical Properties of Q-Pad 3						
Property	Imperial Value	Metric Value	Test Method			
Color	Black	Black	Visual			
Reinforcement Carrier	Fiberglass	Fiberglass	***			
Thickness, (inch) / (mm)	0.005	0.127	ASTM D374			
Hardness, (Shore A)	86	86	ASTM D2240			
Continuous Use Temp., (°F) / (°C)	-76 to 356	-60 to 180	***			
Electrical	Imperial Value	Metric Value	Test Method			
Dielectric Breakdown Voltage, (VAC)	Non-Insulating	Non-Insulating	ASTM D149			
Dielectric Constant, (1000 Hz)	NA	NA	ASTM D150			
Volume Resistivity, (Ohm-meter)	10 ¹	10 ¹	ASTM D257			
Flame Rating	94 V-O	94 V-O	U.L.			
Thermal	Imperial Value	Metric Value	Test Method			
Thermal Conductivity, (W/m-K)	2.0	2.0	ASTM D5470			
Thermal Impedance vs. Pressure						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance, (°C/W)		2.26	1.99	1.76	1.53	1.30
Thermal Impedance, (°C-in ² /W) (I)		0.65	0.48	0.35	0.24	0.16

1). The ASTM D5470 (Bergquist Modified) test fixture was used. The recorded value includes interfacial thermal resistance. These values are given to the customer for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Typical Applications Include

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

Configurations

Available:

- Sheet form
- Die-Cut parts
- Roll form
- With or without pressure sensitive adhesive

We produce thousands of specials. Tooling charges vary depending on tolerances and complexity of the part.

U.L. File Number E59150

Sil-Pad[®]: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others

Product Data Sheet / PDS-0602-001-01; Rev 01